



Printed Circuit Boards  
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

Seite:

# PRINTED CIRCUIT BOARDS

01

4.11.2001

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## Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 210 FR4 100 L71.135 P18\_10

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_210\_FR4\_100\_L71.135\_p18\_10

| Layers   | in $\mu$  | Material | Build-Up | Assembly |                                |
|----------|-----------|----------|----------|----------|--------------------------------|
| Layer-1  | 100 $\mu$ | Copper   |          |          |                                |
|          | 100 $\mu$ | Prepreg  |          |          | (100 $\mu$ PrePreg-Type: 2125) |
|          | 180 $\mu$ | Prepreg  |          |          | (180 $\mu$ PrePreg-Type: 7628) |
|          | 180 $\mu$ | Prepreg  |          |          |                                |
| Layer-2  | 135 $\mu$ | Copper   |          |          |                                |
|          | 710 $\mu$ | L-FR4    |          |          |                                |
| Layer-3  | 135 $\mu$ | Copper   |          |          |                                |
|          | 180 $\mu$ | Prepreg  |          |          |                                |
|          | 180 $\mu$ | Prepreg  |          |          |                                |
|          | 100 $\mu$ | Prepreg  |          |          |                                |
| Layer-99 | 100 $\mu$ | Copper   |          |          |                                |

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